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(54) SEMICONDUCTOR ASSEMBLY AND TEST METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor package assembly which comprises an improved contact structure.

SOLUTION: In a semiconductor package assembly 611, a board 612 which comprises conductive contact pads on a first surface and a second surface and which is composed of an insulating material is contained. In addition, a plurality of semiconductor devices 621 which comprise contact pads faced with the contact pads on the first surface and the second surface of the board 612 are contained. In addition, elastic contact structures 626 by which the contact pads of the semiconductor devices 621 and contact pads held by the board 612 are electrically connected to each other and which are used to support the semiconductor devices in positions at intervals from the surface of the board 612 in such a way that the semiconductor devices 621 exist on a first parallel plane and a second parallel plane on both sides of the board 612 are contained. In addition, contact means 616 which are held by the board 612 and which form elastic contacts with the semiconductor devices 621 via the contact structures 626 are contained.

